

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSVI)

# **TPC8002**

Lithium Ion Battery Applications
Portable Equipment Applications
Notebook PC Applications

• Small footprint due to small and thin package

• Low drain-source ON resistance :  $RDS (ON) = 11.5 \text{ m}\Omega \text{ (typ.)}$ 

 $\bullet~$  High forward transfer admittance :  $|\,Y_{fs}\,|\,$  = 15 S (typ.)

• Low leakage current :  $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 30 \text{ V)}$ 

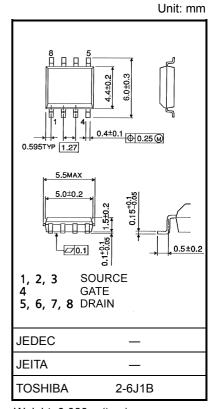
• Enhancement-mode :  $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

### **Maximum Ratings (Ta = 25°C)**

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	30	V	
Drain-gate voltage (R	k <sub>GS</sub> = 20 kΩ)	$V_{DGR}$	30	V	
Gate-source voltage		V <sub>GSS</sub>	±20	٧	
Drain current	DC (Note 1)	I <sub>D</sub>	11	Α	
Diam current	Pulse (Note 1)	$I_{DP}$	44	^	
Drain power dissipati	on (t = 10 s) (Note 2a)	$P_{D}$	2.4	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	P <sub>D</sub>	1.0	W	
Single pulse avalance	ne energy (Note 3)	E <sub>AS</sub>	157	mJ	
Avalanche current		I <sub>AR</sub>	11	Α	
Repetitive avalanche	energy Note 2a) (Note 4)	E <sub>AR</sub>	0.24	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature	range	T <sub>stg</sub>	-55 to 150	°C	

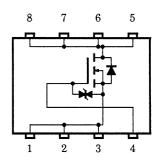
Note: For (Note 1), (Note 2), (Note 3) and (Note 4), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.080 g (typ.)

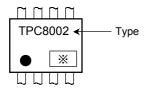
### **Circuit Configuration**



#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R <sub>th (ch-a)</sub>	52.1	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R <sub>th (ch-a)</sub>	125	°C/W

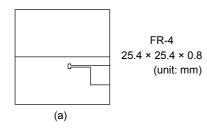
#### Marking (Note 5)

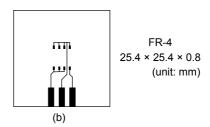


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)





Note 3:  $V_{DD}$  = 24 V,  $T_{ch}$  = 25°C (initial), L = 1.0 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 11 A

Note 4: Reptitve rating; pulse width limited by maximum channel temperature

Note 5: ● on lower left of the marking indicates Pin 1.

\*\* shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively.)

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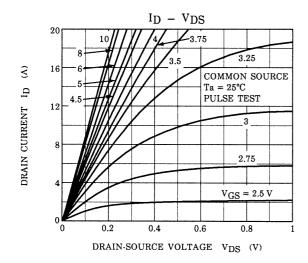
# Electrical Characteristics (Ta = 25°C)

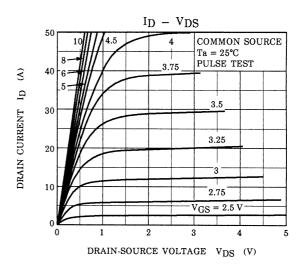
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cut-off current		I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V		_	10	μA
Drain-source breakdown voltage		V <sub>(BR) DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	30	_	_	V
Gate threshold v	Gate threshold voltage		V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	0.8	_	2.0	V
Drain-source ON resistance		R <sub>DS</sub> (ON)	V <sub>GS</sub> = 4 V, I <sub>D</sub> = 5.5 A	_	19	22	mΩ
		R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5.5 A	_	12	14	mΩ
Forward transfer	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 5.5 A	7.5	15	_	S
Input capacitance		C <sub>iss</sub>		_	1425	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	200	_	
Output capacitance		Coss			790	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{10 \text{ V}}{\circ} V \stackrel{\text{I}_{D} = 5.5 \text{ A}}{\circ} V_{OUT}$ $R_{L} = 2.7 \Omega$ $V_{DD} = 15 \text{ V}$	_	11	_	
	Turn-on time	t <sub>on</sub>			19		ne
	Fall time	t <sub>f</sub>		_	25	_	ns
	Turn-off time	t <sub>off</sub>	Duty $\leq$ 1%, $t_{\rm W} = 10 \mu \rm s$	_	100	_	
Total gate charge (Gate-source plus gate-drain)		Qg	$V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 11 \text{ A}$	_	44	_	
Gate-source charge		Q <sub>gs</sub>		_	29	_	nC
Gate-drain ("miller") charge		Q <sub>gd</sub>		_	15	_	

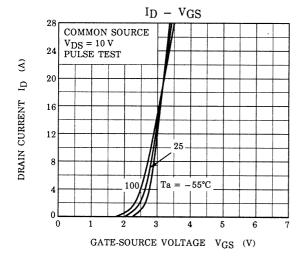
# Source-Drain Ratings and Characteristics (Ta = 25°C)

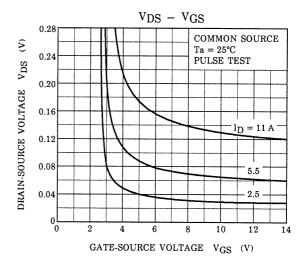
Charact	eristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	44	Α
Forward voltage	(diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 11 A, V <sub>GS</sub> = 0 V	_	_	-1.2	V

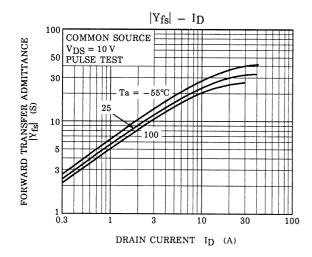
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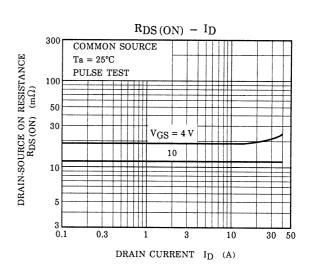




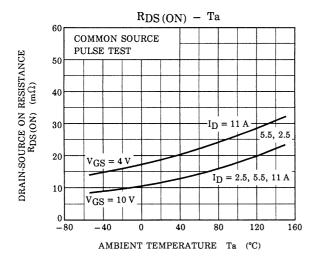


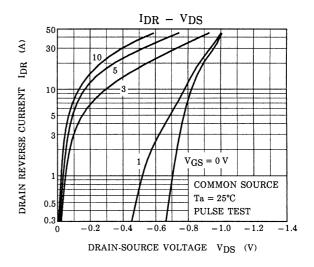


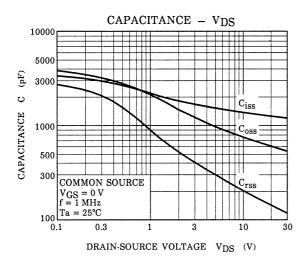


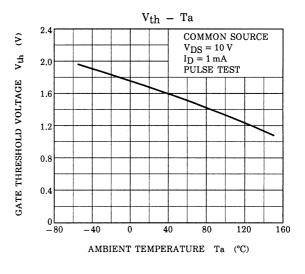


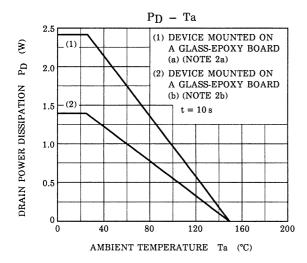
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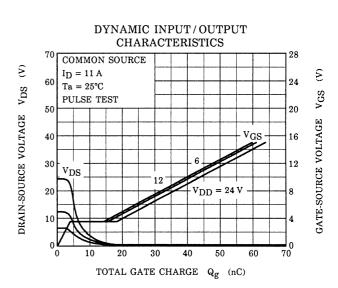




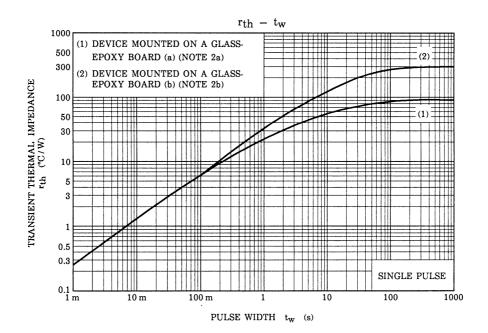


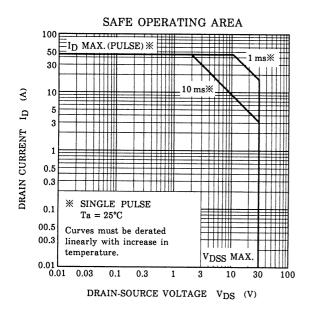


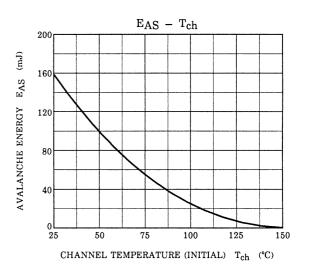


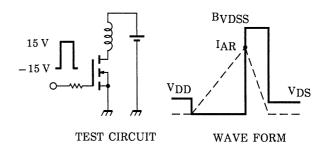


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$$\begin{array}{l} T_{ch} = 25^{\circ}\text{C (Initial)} \\ \text{Peak I}_{AR} = 11 \text{ A}, \ R_G = 25 \ \Omega \end{array} \quad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot (\ \frac{B_{VDSS}}{B_{VDSS} - V_{DD}}) \\ V_{DD} = 24 \text{ V}, \ L = 1.0 \text{ mH} \end{array}$$

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